

A 200 MS/s 98-dB SNR Track-and-Hold in 0.25-um GaN HEMT

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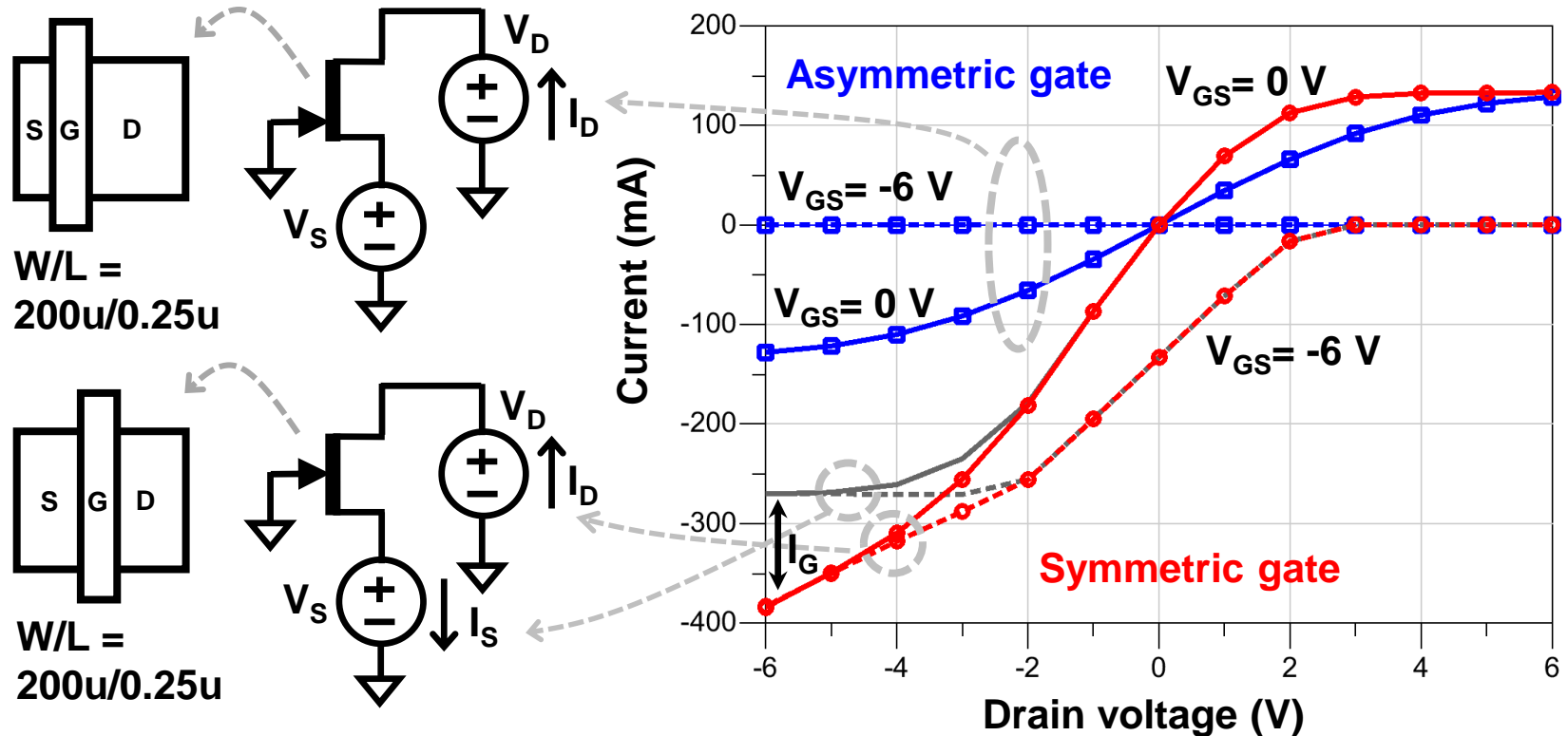
Outline

- **Motivation: Ultra High SNR**
- **GaN HEMT T/H Design Challenge**
- **Proposed Two-Stage GaN HEMT T/H**
- **Measurement Results**

Motivations

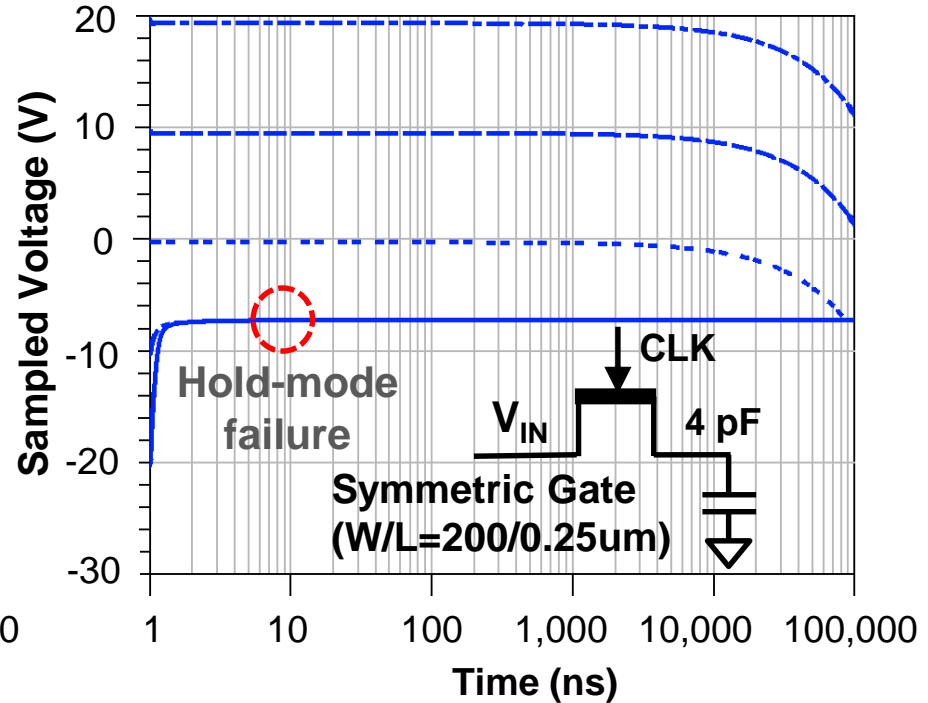
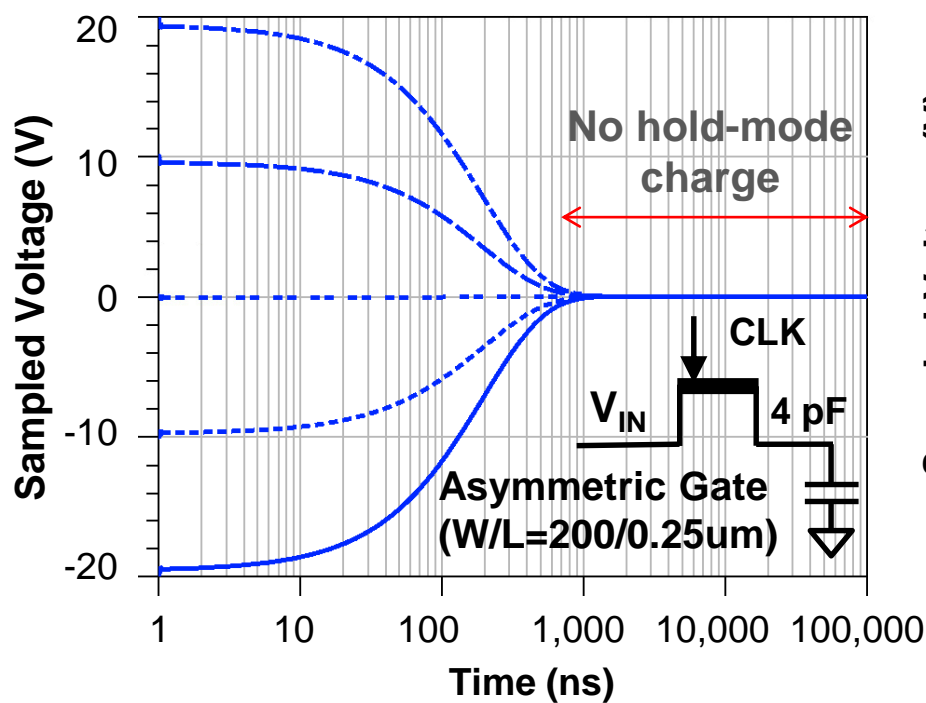
- Track-and-Hold (T/H) for future GaN ADCs with *large signal range*
- High supply voltage capability of GaN provides *ultra high SNR*
- High speed capability of GaN provides *high bandwidth*
- Digital post-processing can significantly suppress *distortion*

Schottky Junction in GaN HEMT



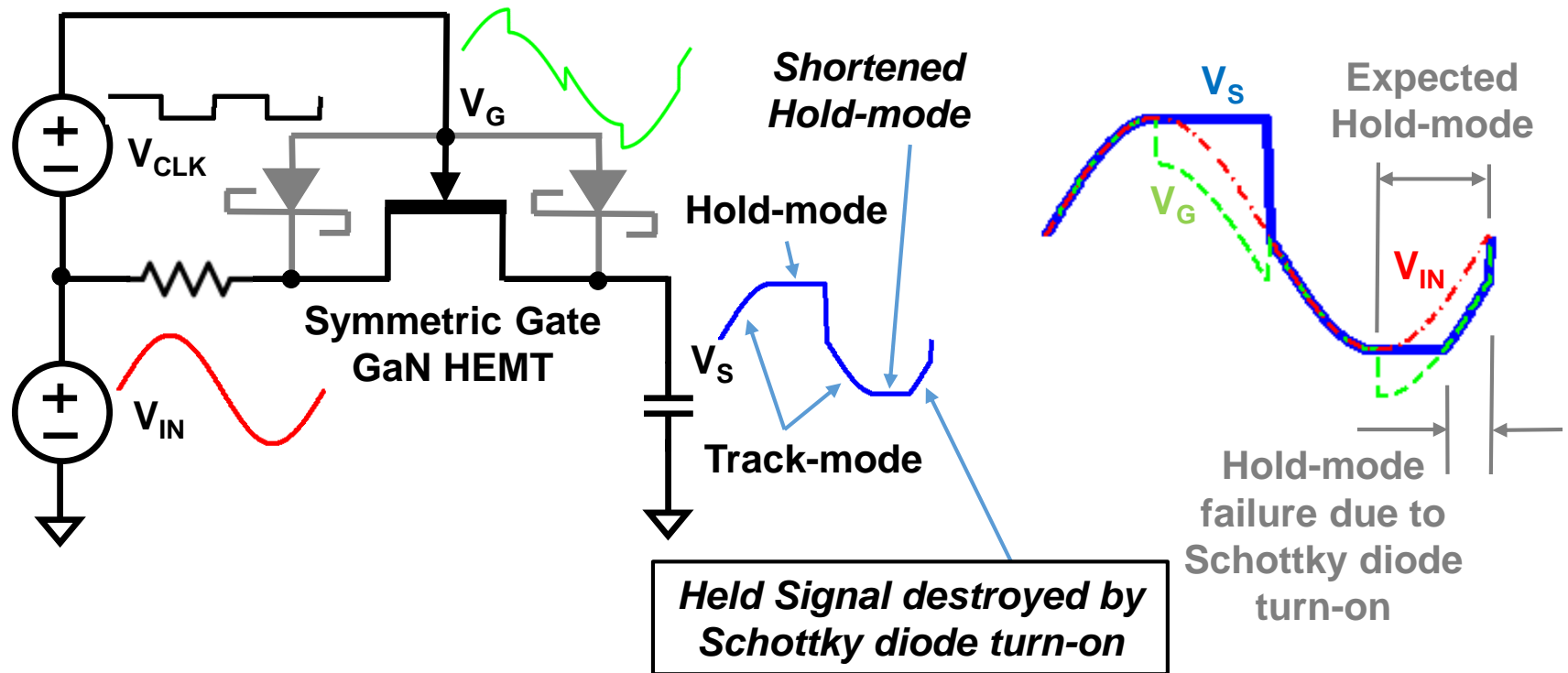
- Gate-source junction has a built-in Schottky diode
- Large gate current introduces permanent damage

Leakage Current in GaN HEMT



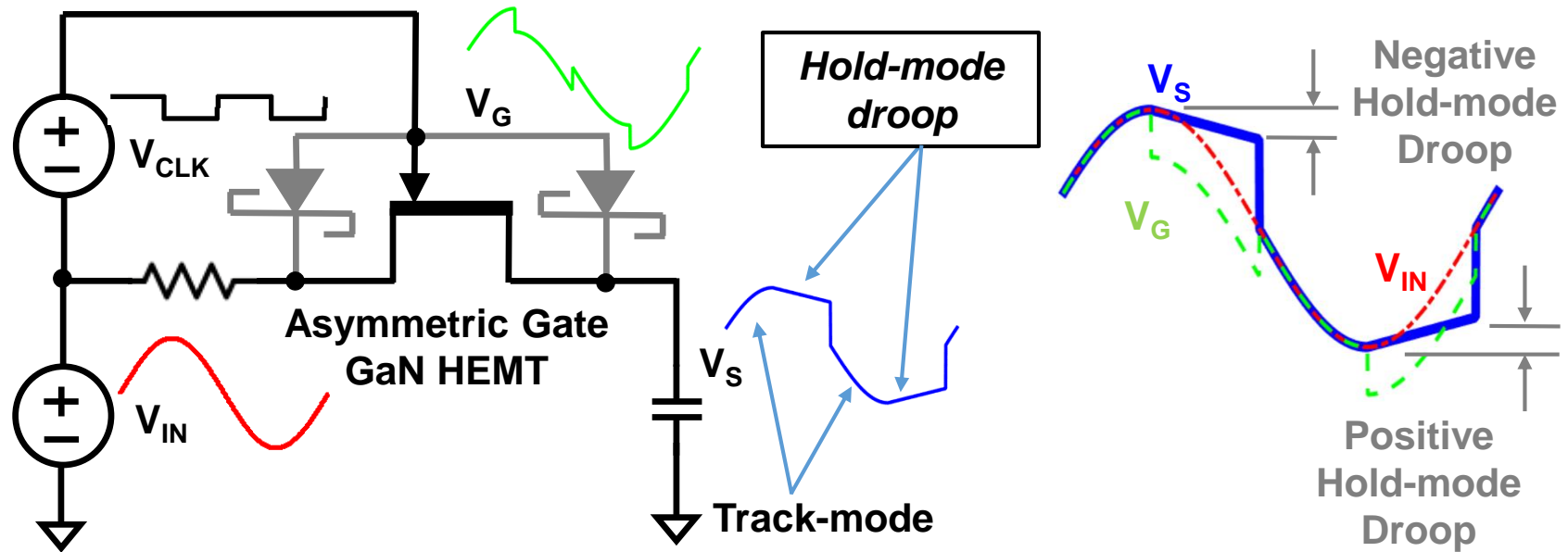
- 1000x smaller leakage current with symmetric gate
- Symmetric devices require a larger clock swing

Gate-Bootstrapping in GaN HEMT with a *Symmetric Gate*



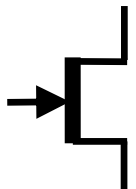
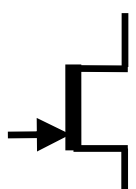
- Very large clock signal swing is required to avoid Schottky diode turn-on

Gate-Bootstrapping in GaN HEMT with an *Asymmetric Gate*



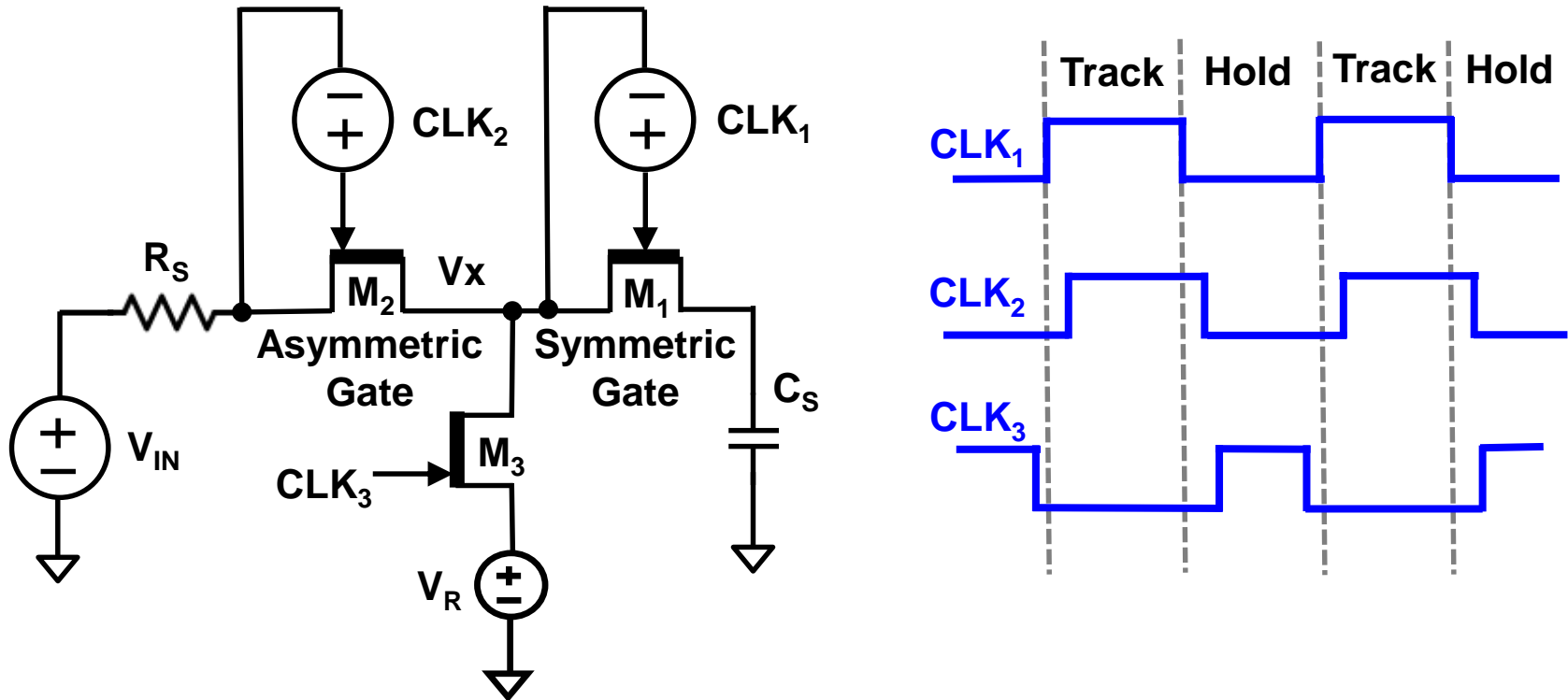
- Hold-mode droop is significant due to the large leakage current

Gate-Bootstrapping GaN HEMT T/H Design Challenges

GaN HEMT Sampling Switch Type	Leakage Current	Schottky Turn-on Voltage (gate-drain)
Symmetric 	Small → Small Droop	Small → High Swing CLK
Asymmetric 	Large → Large Droop	Large → Low Swing CLK

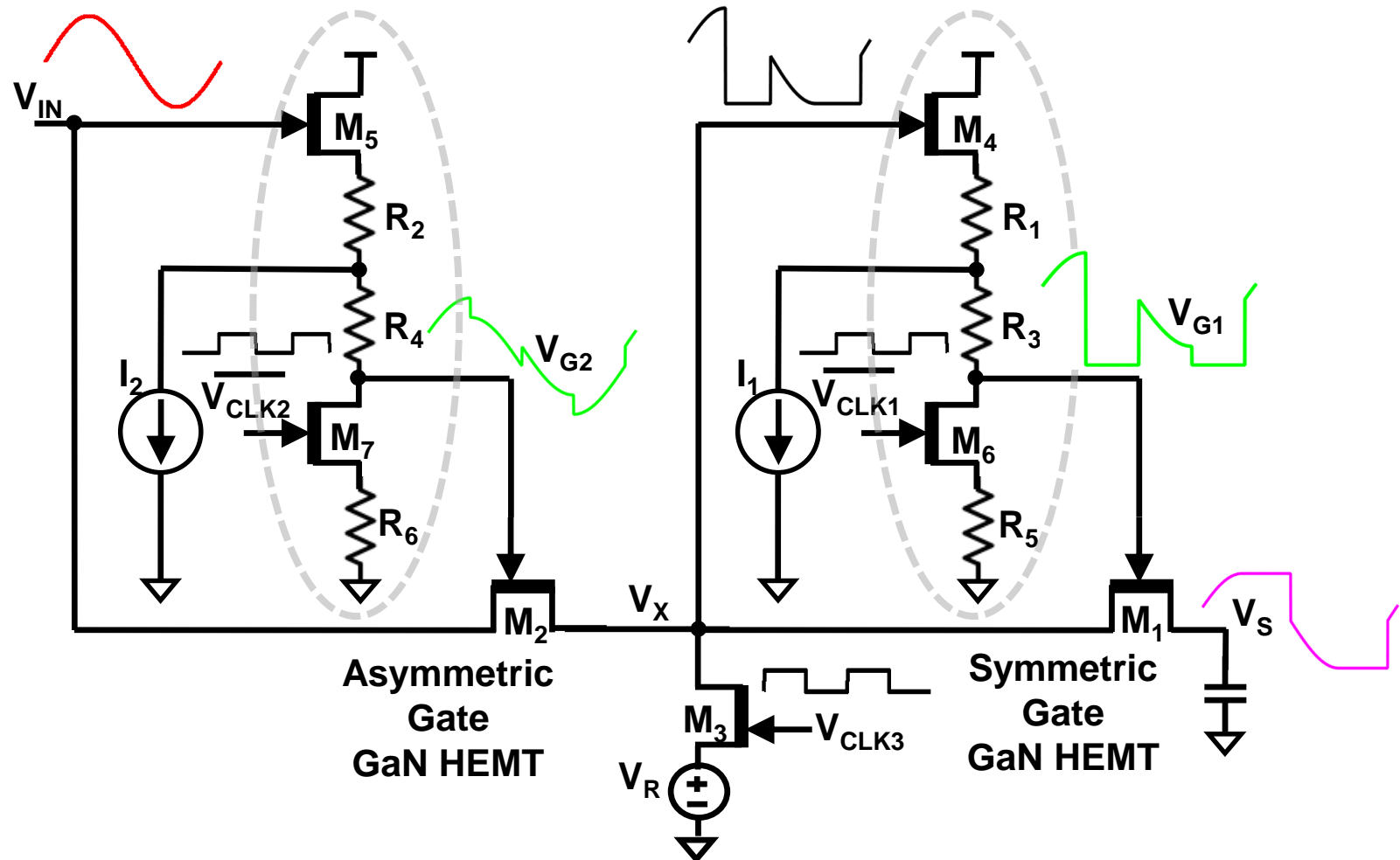
- Challenging to allow “*small hold-mode droop*” and “*low swing sampling clock*” at the same time

Proposed 2-Stage GaN HEMT T/H



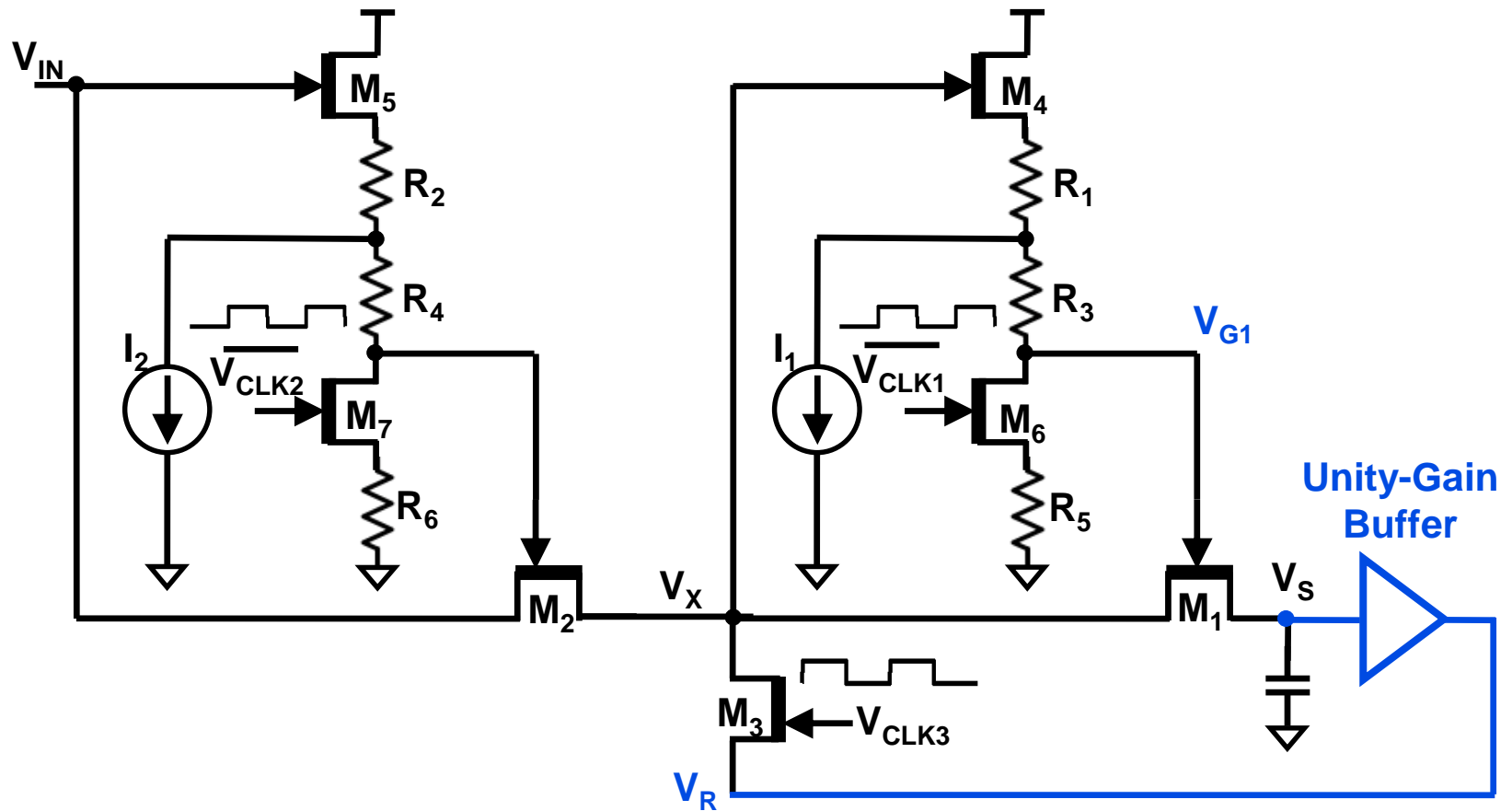
- Takes the advantage of symmetric & asymmetric devices → Allows **Small droop** & **Low swing clock**

N-type GaN HEMT Implementation



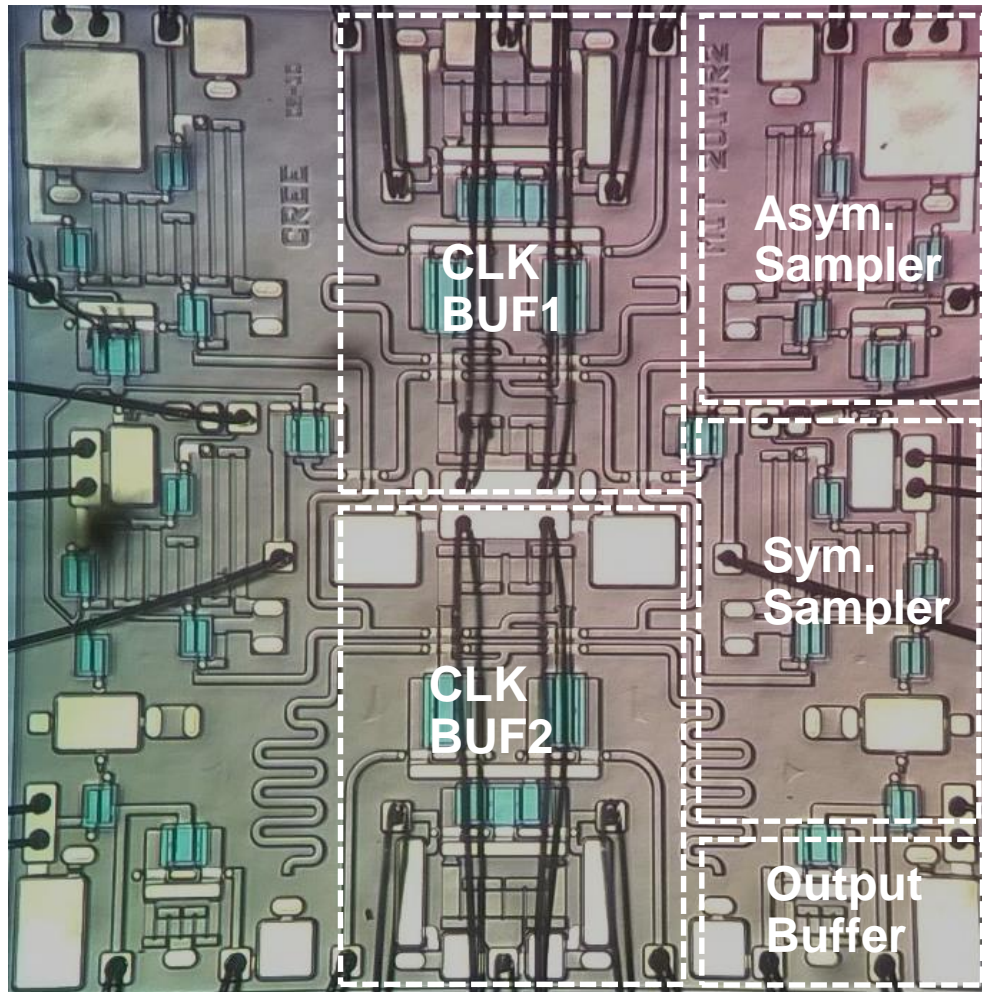
- Switched source follower for gate-bootstrapping
- Most current consumption during hold-mode

Low-Power Operation



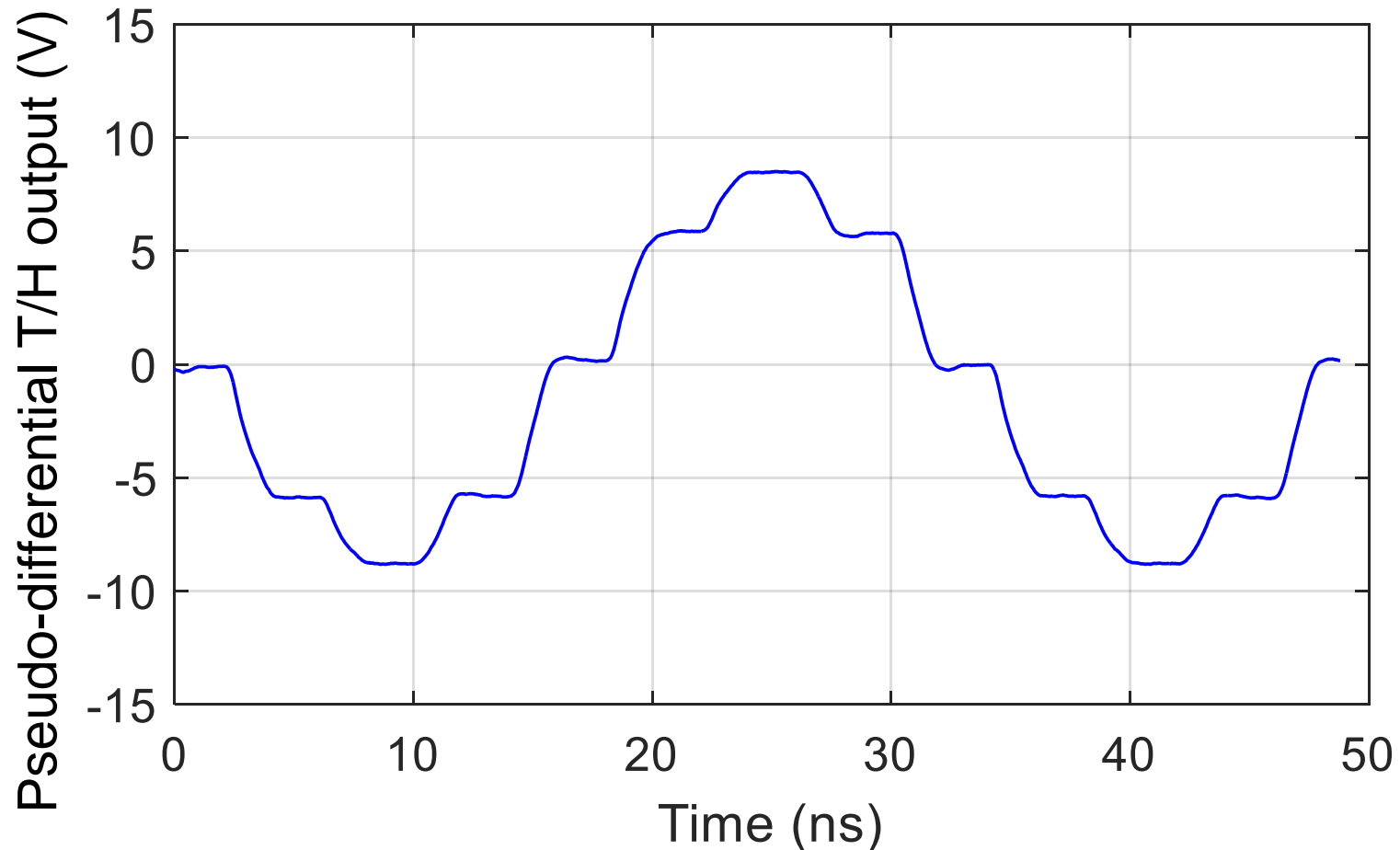
- **Feedback generation of V_R in order to reduce the voltage swing of the gate-bootstrapping clock V_{G1}**

2-Stage GaN HEMT T/H Test Chip



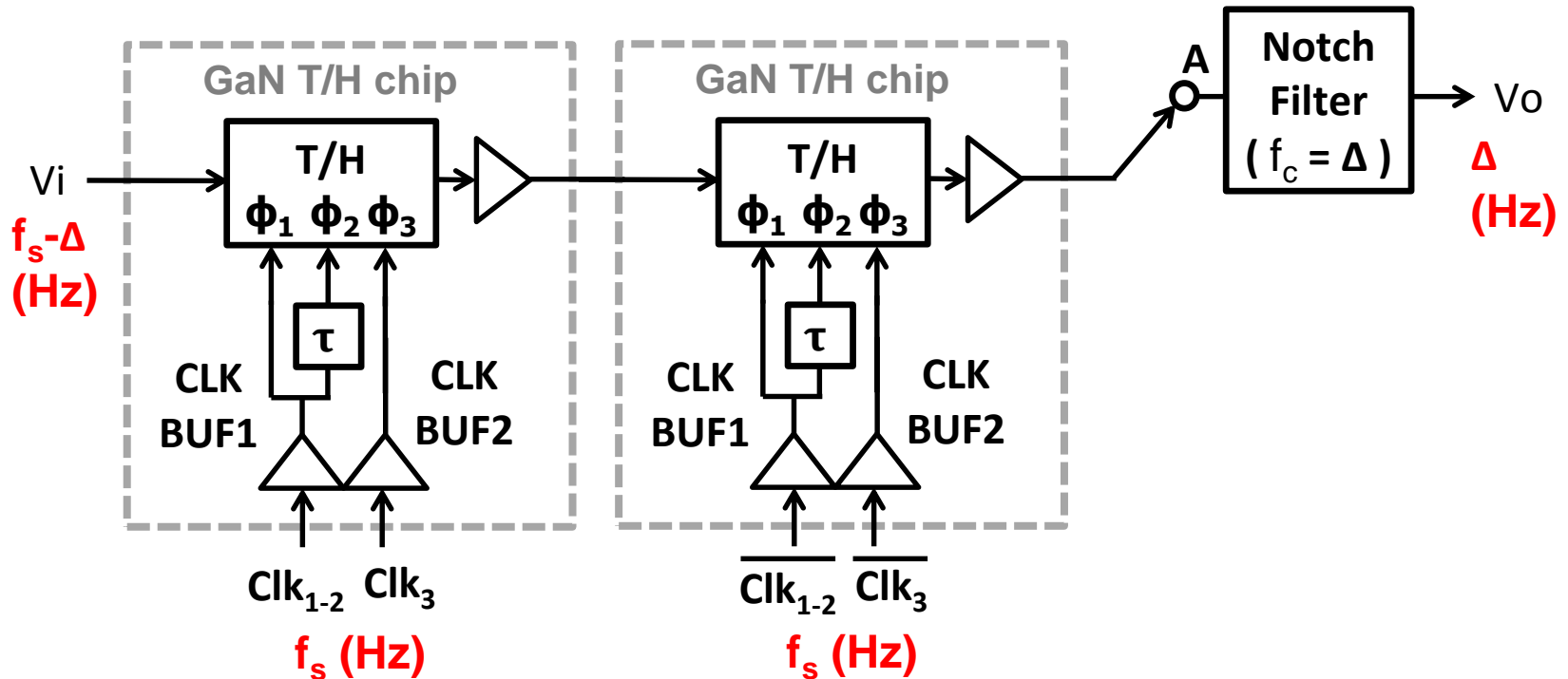
Process	250nm GaN-on-SiC
f_t	10 GHz
Supply	28 V
Size	3 mm x 3 mm
Input	24 V _{pp} p-differential
C_{sample}	6 pF
$f_{\text{sample, max}}$	250 MHz
BW	240 MHz (track-mode)
Current	55 mA (T/H core)

Measured T/H Transient Output



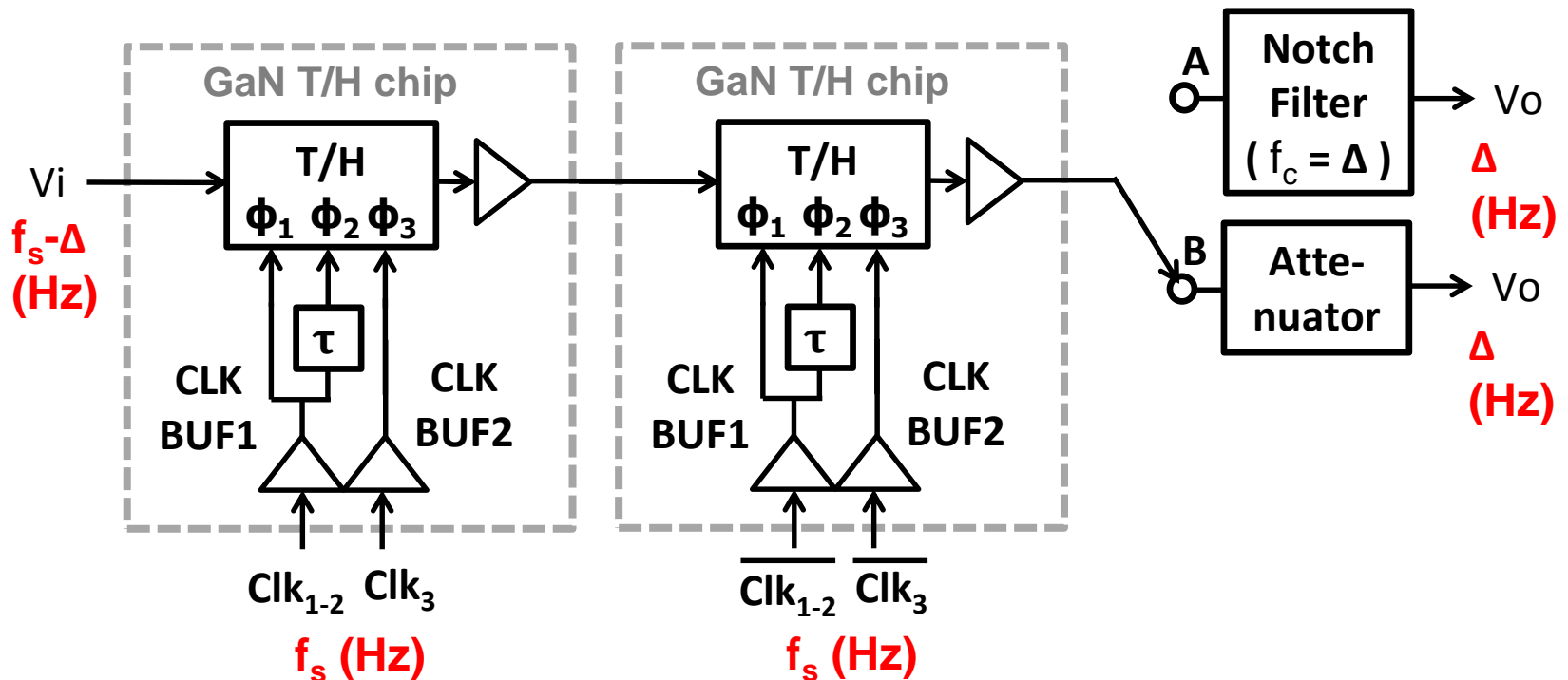
- 250 MS/s with 22- V_{pp} pseudo-differential input

Over 100-dB SNR Measurement on 24-V_{pp} Differential Signal



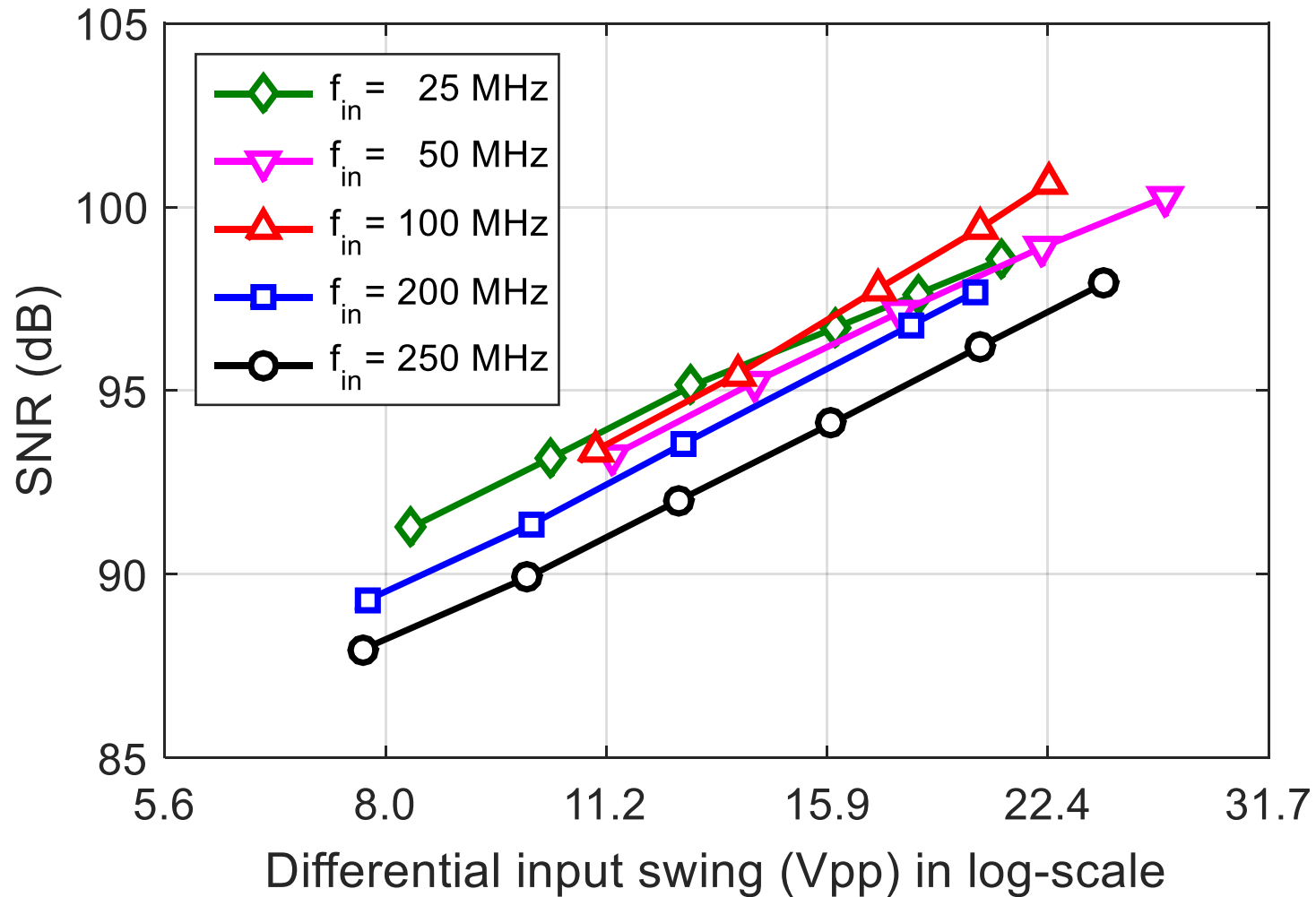
- Step 1 : Noise floor measurement with notch filter

Over 100-dB SNR Measurement on 24-V_{pp} Differential Signal



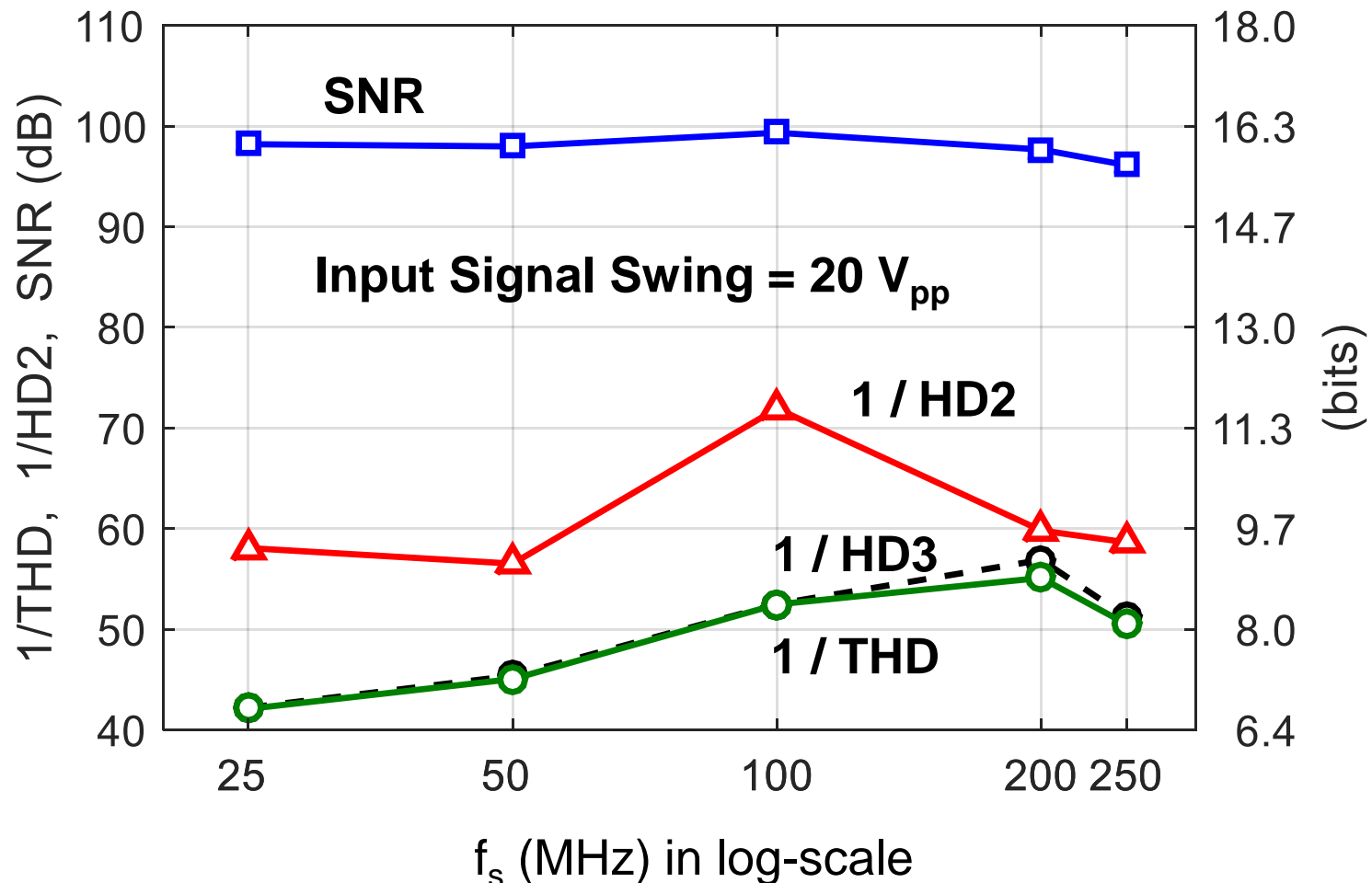
- Step 1 : Noise floor measurement with notch filter
- Step 2 : Dynamic range measurement with attenuator

Measured Signal-to-Noise Ratio



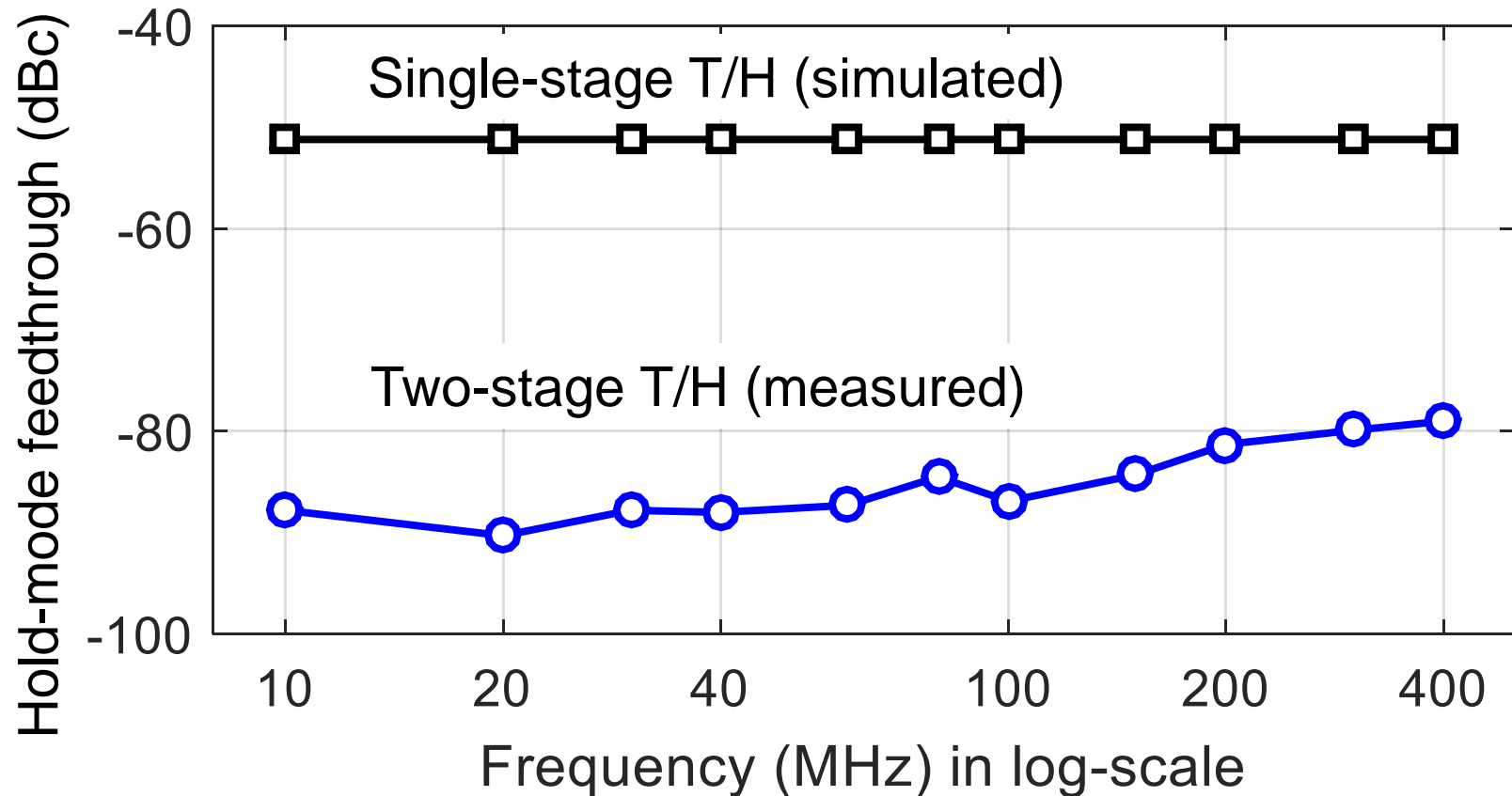
- **101.7-dB peak SNR at 100.1 MS/s with 100-MHz input**

Measured Linearity



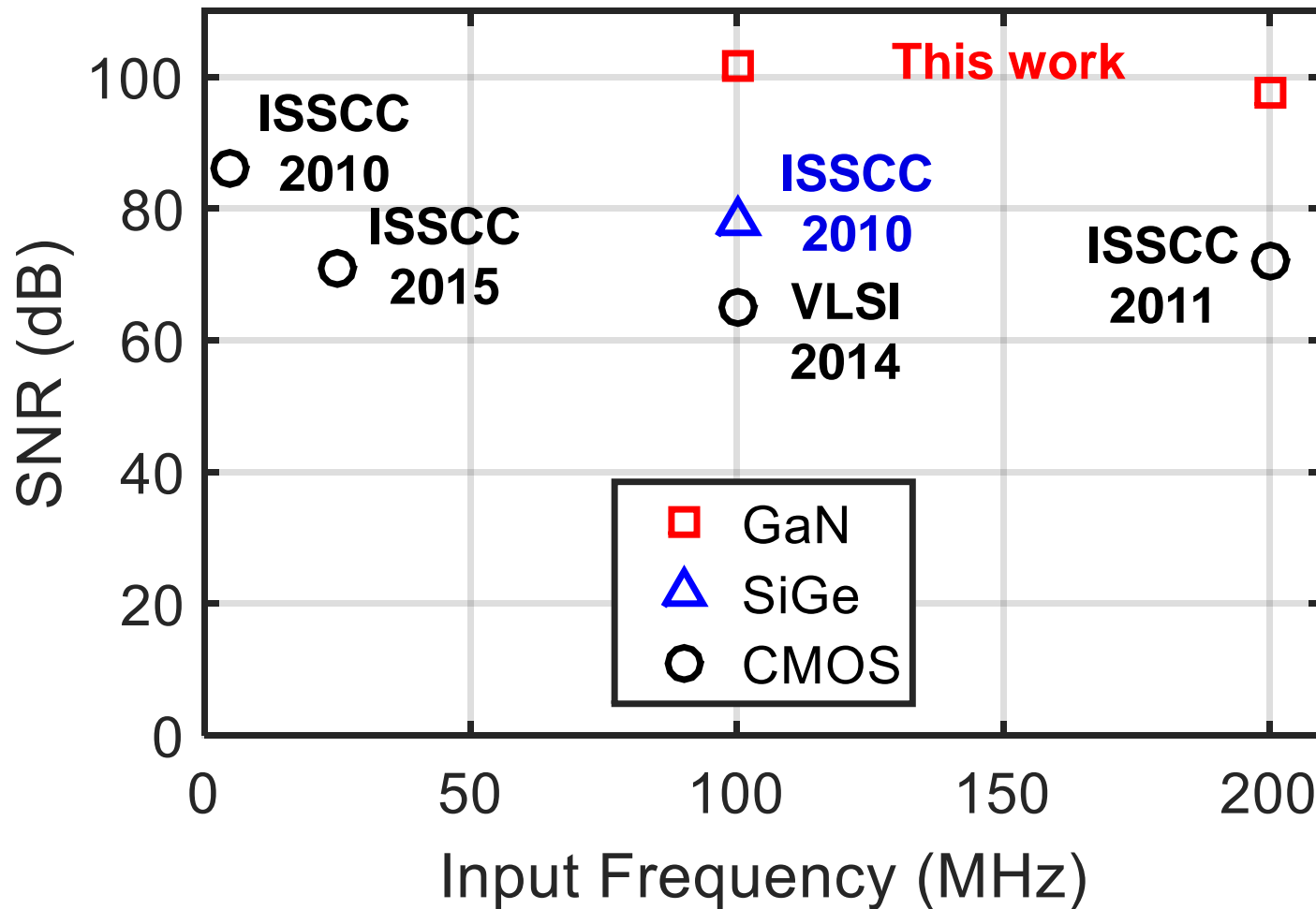
- Linearity can be improved by digital post-processing

Measured Feedthrough



- **More than 30-dB improvement with 2-stage design**

Comparison of High-SNR T/H



Summary

- Implemented a 2-stage GaN HEMT T/H sampler for low-power and low-leakage operation
 - Asymmetric gate transistor in the 1st stage for the low power operation of the 2nd stage
 - Symmetric gate transistor in the 2nd stage for low leakage operation
- Demonstrated the highest reported bandwidth-SNR product enabled by a large signal swing
 - 101.7-dB SNR with 100-MHz 24-V_{pp} pseudo-differential input signal sampled at 100.1 MS/s